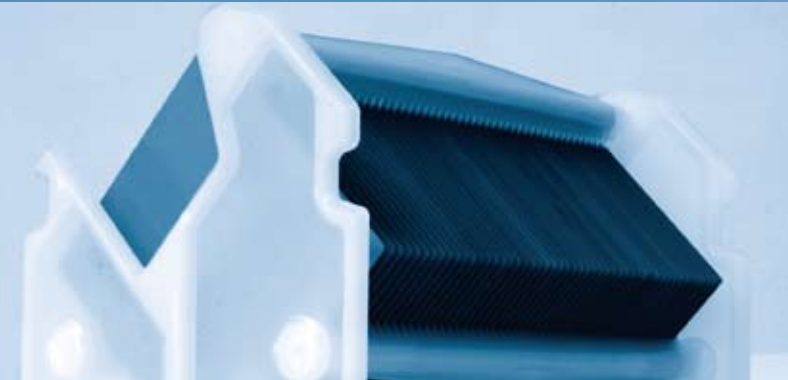


# SOLAR ADC Carrier

R|E|N|A|.



## Fast drying - no shadows and marks

Better solar cells by cleaner surface at reduced drying time.

This unique design is intended for maximum drying performance and is the ideal solution for the patented HF/O<sub>3</sub> process. Design of carrier guarantees maximum exchange of chemical solution.

### Areas of application

- Saw damage etching, texturing
- Oxide/glass etching
- For solar cells or similar products
- For alkaline and acidic solutions
- Superior cleaning and drying techniques

### Features and benefits

- Ultimate solution for surface quality and process speed
- Open construction ensures maximum flow of process solution between wafers
- Small support bars minimise influences on the flow of process solution
- Smallest contact points avoid shadowing and drying marks
- Flat face plates with reference points support the suitability for automatic handling
- Reinforcements reduce floating forces
- 45° orientation of wafers ensures no splash-back when wafers penetrate the surface of the liquid during removal
- When used in RENA wet processing systems the integrated down holding mechanism is automatically activated
- Transponder for MES interface optional





DC Carrier processing

## Technical Data ADC Carrier

<b>Wafer Dimensions</b>	• Size:	100 x 100 mm <sup>2</sup> to 125 x 125 mm <sup>2</sup> , other sizes on application
	• Thickness:	> 150 µm to 400 µm, depending on size < 150 µm on application
	• Slot pitch:	4.76 mm, other pitches on application

<b>Carrier Capacity</b>	25, 50, 100 at pitch 4.76 mm
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Dimensions Carrier	Carrier Capacity	Wafer Size (mm)	Length (mm)	Width (mm)	Height (mm)
	25	100 x 100	145	185	190
		125 x 125	145	185	190
	50	100 x 100	274	185	190
		125 x 125	274	185	190
	100	100 x 100	530	185	190
		125 x 125	530	185	190

<b>Material</b>	• PVDF , PFA
	• Reinforcement: stainless steel (SS), carbon fibre (CFR) optional coatings for SS: epoxy, Halar

<b>Options</b>	• Face plates can be adapted to suit customer's requirements (within limits)
	• Implementation of transponders for product tracking